

# <SPECIFICATION>

SPEC.No. ASDIQ-SPE-028(00)

Date: Jan.28.2022

To :

CUSTOMER'S PRODUCT NAME

ASDI PRODUCT NAME:

SIPM1004A-SERIES

## RECEIPT CONFIRMATION

| UNCONDITIONAL CONSENT |
|-----------------------|
|                       |

| CONDITIONAL CONSENT |
|---------------------|
|                     |

| APPROVED | CHECKED |
|----------|---------|
|          |         |

## ASDI SIGNATURE

| APPROVED     | CHECKED    | PREPARED   |
|--------------|------------|------------|
| Xianglong Li | Liang Wang | Jiayin Cai |



Xiamen ASDI Electronics Co.,Ltd.



# CAUTION WHEN HANDLING

Before use the products, please read this specification.

# CAUTION FOR SAFETY USING

When use the products, be careful to mentioned below for safety using.

## CAUTION

\*The product should be used within 12 monthes.

Focus on the storage conditions.

Solderability may become weak if it exceeds the period.

\*Do not use and store the product in condition of gas corrosion  
(Salt,Acid,Alkaline).

\*The products must be preheated before soldering.

The operating temperature including self-generated heat must be within  $-55\sim+125^{\circ}\text{C}$

\*Rework by soldering iron;Please keep the mentioned conditions in this specification.

\*In case of insert P.C. Board on chassis, do not add mechanical stress to the product.

\*Be careful to arrange of non-magnetic field type inductors.

The error may be caused by magnetic field coupling.

\*In case handle the products, please use wrist strap for ground static discharge on human body.

The product keeps away from magnet or magnetized things.

\*Do not use the product beyond the mentioned conditions in this specification.

\*About an application

The products listed on this specification sheet are intended for use in general electronic equipment

(AV equipment, telecommunications equipment, home appliances, amusement equipment, computer equipment, personal equipment, office equipment, measurement equipment, industrial robots) under a normal operation and use condition.

\*The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below or for any other use exceeding the range or conditions set forth in this specification sheet.

- |                                |  |
|--------------------------------|--|
| 1)Aerospace/Aviation equipment | 6)Transportation control equipment   |
| 2)Military equipment           | 7)Power-generation control equipment<br>which directly endanger human life   |
| 3)Seabed equipment             | 8)Atomic energy-related equipment  |
| 4)Safety equipment             | 9)Other applications that are not<br>considered general-purpose applications |
| 5)Medical equipment            |  |

If you intend to use the products in the following applications, please contact our sales office.

Transportation equipment (cars, electric trains, ships, etc.), Public information-processing equipment, Electric heating apparatus / burning equipment, Disaster prevention/crime prevention equipment

When using this product in general-purpose applications, you are kindly requested to take into consideration securing protection circuit/equipment or providing backup circuits, etc., to ensure higher safety.

Xiamen ASDI Electronics Co.,Ltd.

DWG.No.  
ASDIQ-SPE-028(00)

ISSUE

|          |                                   |                    |
|----------|-----------------------------------|--------------------|
| CUSTOMER | ASDI PART No.<br>SIPM1004A-SERIES | CUSTOMER'S DWG NO. |
|----------|-----------------------------------|--------------------|

1.Applications

Note PC power system, incl. IMVP-6, Switch and servers,Base stations  
Battery powered devices,SSD modules,DC/DC converter .

2.INDEX

| Listed item                 | Attachment&Tables | Page |
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| 10.Note                     | Please see (10)   | 8/8  |
| 11.Standard test conditions |                   |      |
| —                           |                   |      |

3.Manufacturing Location

China

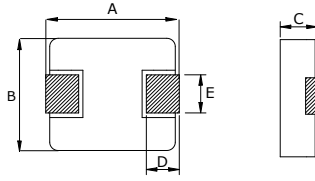
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(1)Features

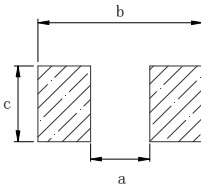
- ROHS, Halogen Free and REACH compliance
- High rated current
- 125℃ maximum total temperature operation
- 11.5×10.3×4.0mm maximum surface mount package
- Low core loss
- Ultra low buzz noise due to molding construction

(2)Dimensions



| Series    | A(mm)   | B(mm)    | C(mm)   | D(mm)   | E(mm)   |
|-----------|---------|----------|---------|---------|---------|
| SIPM1004A | 11.5MAX | 10.0±0.3 | 3.8±0.2 | 2.0±0.5 | 3.0±0.5 |

(3)Recommend Land Pattern



| a typ | b typ | c typ |
|-------|-------|-------|
| 5.40  | 13.6  | 4.10  |

Marking

The inductor is marked with a 3-digit code

| Nominal Inductance |               |
|--------------------|---------------|
| Example            | Nominal Value |
| 1R0                | 1.0 μH        |
| 100                | 10 μH         |
| 101                | 100 μH        |

Note: Using Ink for marking



(4)Part Numbering

**SIPM**      **1004**      **A**      -      **1R5**      **M**  
 A              B              C                              D              E  
 A: Series  
 B: Dimension  
 C: Material  
 D: Inductance      1R5=1.5μH  
 E: Inductance Tolerance      M=±20%

(5)Electrical Specifications

Table 1

| ASDI Part Number | Inductance         | DC Resistance | Saturation Current | Heating Rating Current |
|------------------|--------------------|---------------|--------------------|------------------------|
|                  | L0(μH)             | DCR (mΩ)      | I sat(A)           | I rms (A)              |
|                  | ±20%<br>100 kHz/1V | MAX           | TYP.               | TYP.                   |
| SIPM1004A-R15M   | 0.15               | 0.65          | 75.00              | 45.00                  |
| SIPM1004A-R22M   | 0.22               | 1.00          | 60.00              | 35.00                  |
| SIPM1004A-R30M   | 0.30               | 1.10          | 45.00              | 35.00                  |
| SIPM1004A-R36M   | 0.36               | 1.20          | 45.00              | 30.00                  |
| SIPM1004A-R47M   | 0.47               | 1.70          | 40.00              | 30.00                  |
| SIPM1004A-R56M   | 0.56               | 1.80          | 33.00              | 25.00                  |
| SIPM1004A-R68M   | 0.68               | 2.40          | 30.00              | 23.00                  |
| SIPM1004A-R80M   | 0.80               | 2.70          | 29.00              | 23.00                  |
| SIPM1004A-1R0M   | 1.00               | 3.30          | 28.00              | 19.00                  |

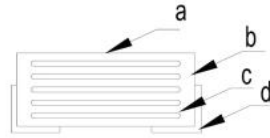
| ASDI Part Number | Inductance               | DC Resistance     | Saturation Current | Heating Rating Current |
|------------------|--------------------------|-------------------|--------------------|------------------------|
|                  | L0( $\mu$ H)             | DCR (m $\Omega$ ) | I sat(A)           | I rms (A)              |
|                  | $\pm 20\%$<br>100 kHz/1V | MAX               | TYP.               | TYP.                   |
| SIPM1004A-1R5M   | 1.50                     | 4.20              | 24.00              | 16.00                  |
| SIPM1004A-2R2M   | 2.20                     | 7.00              | 16.50              | 12.00                  |
| SIPM1004A-3R3M   | 3.30                     | 11.8              | 16.00              | 11.00                  |
| SIPM1004A-4R7M   | 4.70                     | 20.0              | 13.00              | 9.00                   |
| SIPM1004A-6R8M   | 6.80                     | 25.0              | 12.00              | 8.50                   |
| SIPM1004A-8R2M   | 8.20                     | 27.0              | 9.00               | 8.00                   |
| SIPM1004A-100M   | 10.0                     | 30.0              | 8.50               | 7.80                   |
| SIPM1004A-150M   | 15.0                     | 45.0              | 7.00               | 6.50                   |
| SIPM1004A-220M   | 22.0                     | 66.0              | 5.50               | 5.00                   |
| SIPM1004A-330M   | 33.0                     | 92.0              | 4.80               | 4.40                   |
| SIPM1004A-470M   | 47.0                     | 145.0             | 3.50               | 3.30                   |
| SIPM1004A-680M   | 68.0                     | 195.0             | 3.00               | 2.50                   |
| SIPM1004A-820M   | 82.0                     | 285.0             | 2.80               | 2.30                   |
| SIPM1004A-101M   | 100.0                    | 340.0             | 2.30               | 2.00                   |

Notes

1. All test data is referenced to 25 °C ambient
2. Operating temperature range - 55 °C to + 125 °C
3. I rms (A):DC current (A) that will cause an approximate  $\Delta T$  of 40 °C(reference ambient temperature is 25 °C)
4. I sat(A):DC current (A) that will cause L0 to drop approximately 30 %
5. The part temperature (ambient + temp rise) should not exceed 125 °C under worst case operating conditions.  
Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

(6)Structure and Components

| Symbol | Components | Material                   |
|--------|------------|----------------------------|
| a      | Marking    | Ink (black)                |
| b      | Core       | Alloy Spongy Powder        |
| c      | Wire       | Polyamideimide copper wire |
| d      | Terminal   | Copper plated with Sn      |



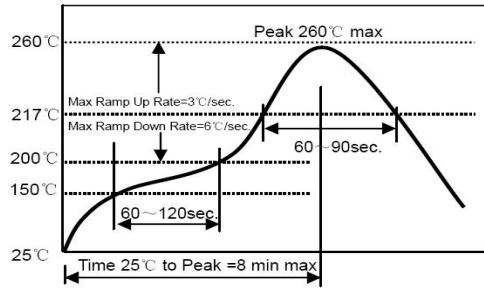
(7)Reliability Tests

| Mechanical Reliability |                          |  |  |
|------------------------|--------------------------|--|--|
| No.                    | Test item                | Performance  | Test details   |
| 1                      | Solderability            | 1. No case deformation or change in appearance<br>2. New solder coverage more than 95% | 1.Preheat: 155°C±5°C , 60S±2S<br>2.Solder: lead-free.<br>3.Temperature: 240°C±5°C ,<br>flux 3.0S±0.5S.   |
| 2                      | Mechanical shock         | 1. No case deformation or change in appearance<br>2. $\Delta L/Lo \cong \pm 10\%$      | 1. Acceleration: 100G<br>2. Pulse time: 6ms<br>3. 3 times in each positive and negative direction of 3 mutual perpendicular directions   |
| 3                      | Mechanical vibration     | 1.No case deformation or change in appearance<br>2. $\Delta L/Lo \cong \pm 10\%$       | 1. Reflow: 2times<br>2. Frequency: 10HZ~55HZ~10HZ, 20 Min/Cycles<br>3. Amplitude: 1.52 mm<br>4. Directions: X,Y,Z<br>5. Time: 12 cycle / direction   |
| Reliability Test       |                          |  |  |
| No.                    | Test item                | Performance  | Test details   |
| 4                      | Thermal shock test       | Inductance change:<br>Within $\pm 10\%$ Without distinct damage in appearance          | 1. First -55°C for 30 minutes, last 125°C for 30 minutes as 1 cycle. Go through 1000 cycles.<br>2. Max transfer time is 3 minutes.<br>3. Measured at room temperature after placing for 24±2 hours |
| 5                      | Humidity Resistance      | Inductance change:<br>Within $\pm 10\%$ Without distinct damage in appearance          | 1.Reflow 2 times,<br>2.85°C,85%RH,1000 hours<br>3.Measured at room temperature after placing for 24±2 hours  |
| 6                      | Low temperature storage  | Inductance change:<br>Within $\pm 10\%$ Without distinct damage in appearance          | 1. Temperature: -55 ± 2°C<br>2. Time: 1000 hours<br>3. Measured at room temperature after placing for 24±2 hours   |
| 7                      | High temperature storage | Inductance change:<br>Within $\pm 10\%$ Without distinct damage in appearance          | 1. Temperature: +125 ± 2°C<br>2. Time: 1000 hours<br>3. Measured at room temperature after placing for 24±2 hours  |

**Recommended Soldering Technologies**

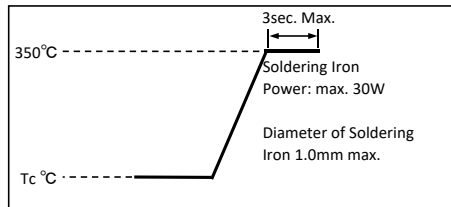
**(8)Soldering and Mounting**  
8-1,Re-flowing Profile

Preheat condition: 150 ~200°C/60~120sec.  
 Allowed time above 217°C: 60~90sec.  
 Max temp: 260°C  
 Max time at max temp: 10 sec.  
 Solder paste: Sn/3.0Ag/0.5Cu  
 Allowed Reflow time: 2x max



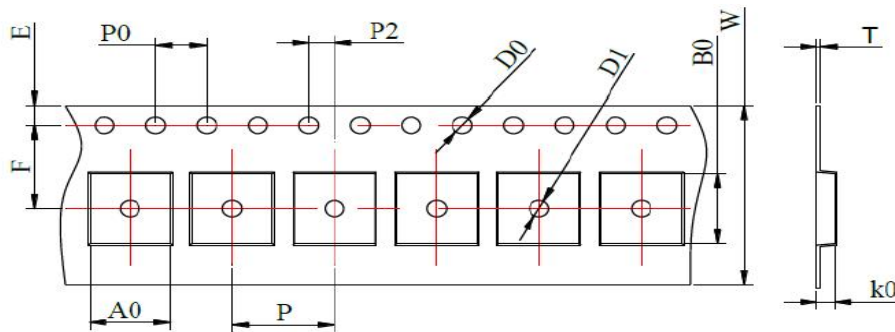
8-2,Iron Soldering Profile

Iron soldering power: Max. 30W  
 Pre-heating: 150°C/60sec.  
 Soldering Tip temperature: 350°C Max.  
 Soldering time: 3sec. Max.  
 Solder paste: Sn/3.0Ag/0.5Cu  
 Max.1 times for iron soldering



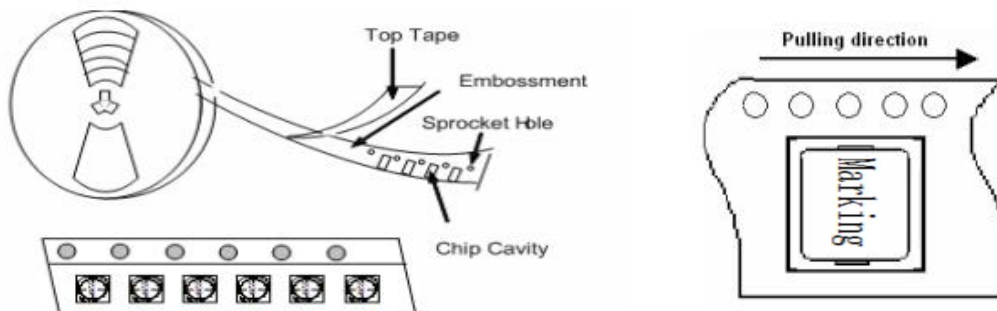
**(9)Packaging Information**

9-1,Tape Packaging Dimensions(Unit: mm)



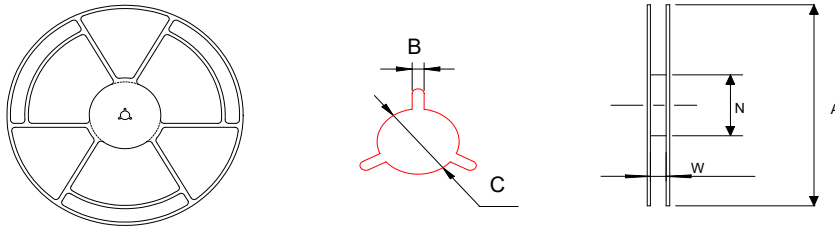
| Type      | Tape Dimensions (mm) |        |       |        |         |         |           |          |          |         |          |          |
|-----------|----------------------|--------|-------|--------|---------|---------|-----------|----------|----------|---------|----------|----------|
|           | W                    | P      | P0    | P2     | D0      | D1      | T         | A0       | B0       | K0      | E        | F        |
| SIPM1004A | 24±0.3               | 16±0.1 | 4±0.1 | 2±0.05 | 1.5±0.1 | 1.5±0.1 | 0.35±0.05 | 10.4±0.1 | 11.6±0.1 | 4.3±0.1 | 1.75±0.1 | 11.5±0.1 |

**Taping Drawings (UNIT:mm)**





9-2, Reel Dimensions (Unit: mm)



| A       | W        | N        | B        | C        |
|---------|----------|----------|----------|----------|
| 330±2.0 | 24.0±0.5 | 97.0±0.5 | 2.20±0.5 | 13.0±0.2 |

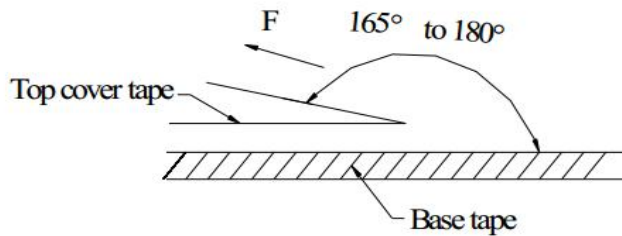
9-3, Packaging Quantity (PCS)

| Type      | Standard Quantity |                         |                            |
|-----------|-------------------|-------------------------|----------------------------|
|           | Reel              | Inner box               | Carton box                 |
| SIPM1004A | 500 pcs / reel    | 2 Reel / box (1000 pcs) | 4 Middle boxes, (4000 pcs) |

9-4, Peel force of top cover tape

The peel speed shall be about 300mm/minute

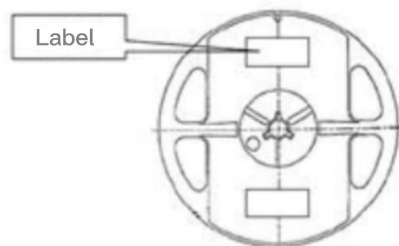
The peel force of top cover tape shall be between 0.1 to 1.3 N



9-5, Reel Label

Label on the reel

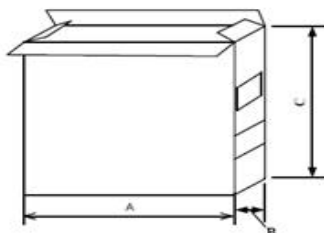
- Customer's part Number
- Lot Number
- Quantity
- Date code



Shipping Label

- Customer's part Number
- Manufacturer's part Number
- Quantity
- Date code

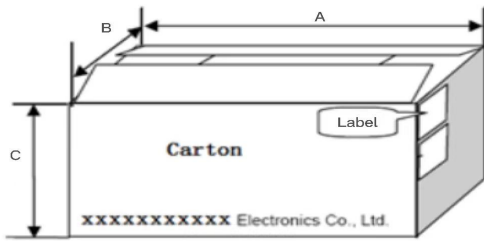
9-6, Inner Box



| Packing Type | A (mm) | B (mm) | C (mm) |
|--------------|--------|--------|--------|
| Inner Box    | 335    | 70     | 340    |

|         |                   |             |
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9-7, Carton



| Packing Type | A (mm) | B (mm) | C (mm) |
|--------------|--------|--------|--------|
| Type         | 360    | 360    | 360    |

(10)Note

·Storage Conditions

To maintain the solderability of terminal electrodes:

1. ASDI products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
2. Temperature: 5 to 30deg.C, Humidity: 75% Max.
3. Recommended products should be used within 24 months form the time of delivery.
4. The packaging material should be kept where no chlorine or sulfur exists in the air.

·Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

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单击下面可查看定价，库存，交付和生命周期等信息

[>>ASDI](#)